

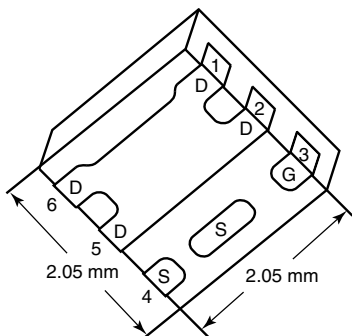


# P-Channel 20 V (D-S) MOSFET

## PRODUCT SUMMARY

| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω) Max.        | I <sub>D</sub> (A) | Q <sub>g</sub> (Typ.) |
|---------------------|-------------------------------------|--------------------|-----------------------|
| - 20                | 0.0165 at V <sub>GS</sub> = - 4.5 V | - 12 <sup>a</sup>  | 23 nC                 |
|                     | 0.0185 at V <sub>GS</sub> = - 3.7 V | - 12 <sup>a</sup>  |                       |
|                     | 0.0300 at V <sub>GS</sub> = - 2.5 V | - 12 <sup>a</sup>  |                       |

PowerPAK SC-70-6L-Single



Ordering Information:  
SiA445EDJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

## FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Thermally Enhanced PowerPAK<sup>®</sup> SC-70 Package
  - Small Footprint Area
  - Low On-Resistance
- 100 % R<sub>g</sub> Tested
- Built in ESD Protection with Zener Diode
- Typical ESD Performance: 2000 V
- Compliant to RoHS Directive 2002/95/EC

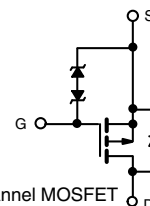
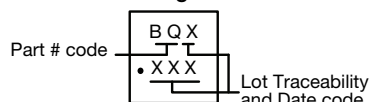


RoHS  
COMPLIANT  
HALOGEN  
FREE

## APPLICATIONS

- Smart Phones, Tablet PCs, Mobile Computing
  - Battery Switch
  - Charger Switch
  - Load Switch

## Marking Code



P-Channel MOSFET

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)

| Parameter                                                    | Symbol                            | Limit                  | Unit                   |
|--------------------------------------------------------------|-----------------------------------|------------------------|------------------------|
| Drain-Source Voltage                                         | V <sub>DS</sub>                   | - 20                   | V                      |
| Gate-Source Voltage                                          | V <sub>GS</sub>                   | ± 12                   |                        |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)           | I <sub>D</sub>                    | T <sub>C</sub> = 25 °C | - 12 <sup>a</sup>      |
|                                                              |                                   | T <sub>C</sub> = 70 °C | - 12 <sup>a</sup>      |
|                                                              |                                   | T <sub>A</sub> = 25 °C | - 11.8 <sup>b, c</sup> |
|                                                              |                                   | T <sub>A</sub> = 70 °C | - 9.5 <sup>b, c</sup>  |
| Pulsed Drain Current (t = 300 μs)                            | I <sub>DM</sub>                   | - 50                   | A                      |
| Continuous Source-Drain Diode Current                        | I <sub>S</sub>                    | T <sub>C</sub> = 25 °C | - 12 <sup>a</sup>      |
|                                                              |                                   | T <sub>A</sub> = 25 °C | - 2.9 <sup>b, c</sup>  |
| Maximum Power Dissipation                                    | P <sub>D</sub>                    | T <sub>C</sub> = 25 °C | 19                     |
|                                                              |                                   | T <sub>C</sub> = 70 °C | 12                     |
|                                                              |                                   | T <sub>A</sub> = 25 °C | 3.5 <sup>b, c</sup>    |
|                                                              |                                   | T <sub>A</sub> = 70 °C | 2.2 <sup>b, c</sup>    |
| Operating Junction and Storage Temperature Range             | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 150            | °C                     |
| Soldering Recommendations (Peak Temperature) <sup>d, e</sup> |                                   | 260                    |                        |

## THERMAL RESISTANCE RATINGS

| Parameter                                   | Symbol            | Typical | Maximum | Unit |
|---------------------------------------------|-------------------|---------|---------|------|
| Maximum Junction-to-Ambient <sup>b, f</sup> | R <sub>thJA</sub> | 28      | 36      | °C/W |
| Maximum Junction-to-Case (Drain)            | R <sub>thJC</sub> | 5.3     | 6.5     |      |

Notes:

- Package limited.
- Surface mounted on 1" x 1" FR4 board.
- t = 5 s.
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under steady state conditions is 80 °C/W.

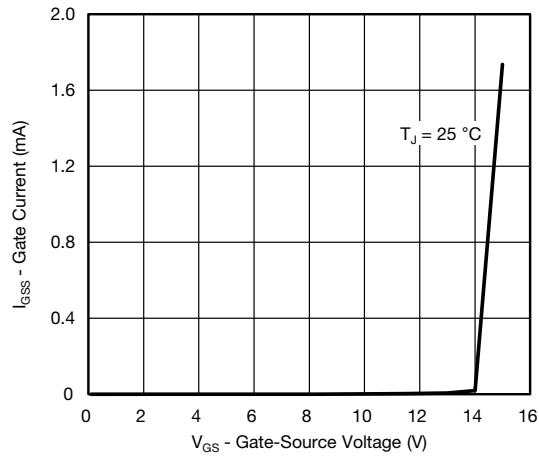
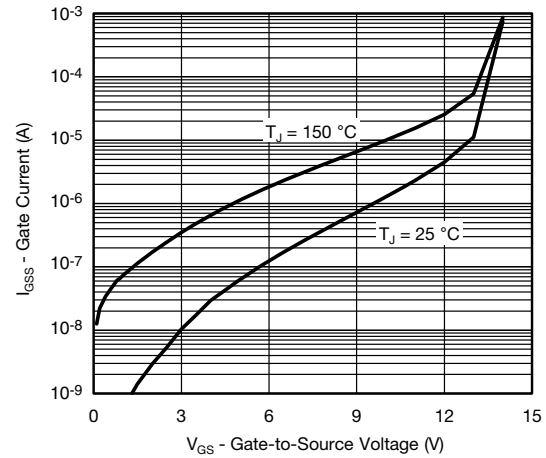
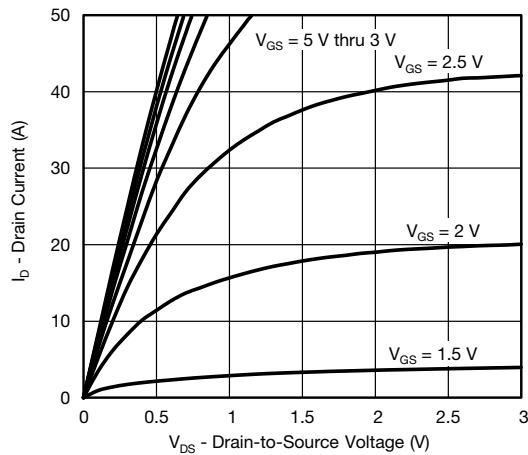
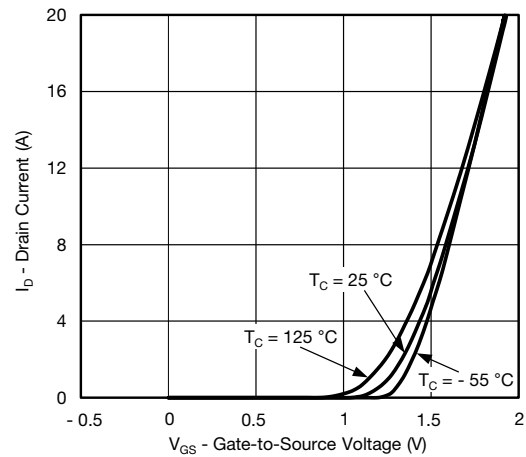
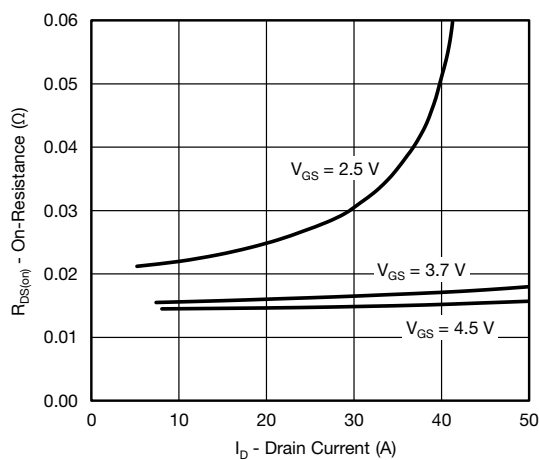
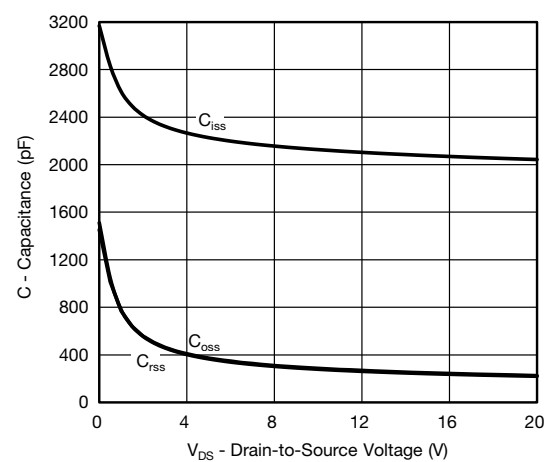
| SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted) |                                      |                                                                                                                              |       |        |        |       |
|-----------------------------------------------------------------|--------------------------------------|------------------------------------------------------------------------------------------------------------------------------|-------|--------|--------|-------|
| Parameter                                                       | Symbol                               | Test Conditions                                                                                                              | Min.  | Typ.   | Max.   | Unit  |
| Static                                                          |                                      |                                                                                                                              |       |        |        |       |
| Drain-Source Breakdown Voltage                                  | V <sub>DS</sub>                      | V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA                                                                             | - 20  |        |        | V     |
| V <sub>DS</sub> Temperature Coefficient                         | ΔV <sub>DS</sub> /T <sub>J</sub>     | I <sub>D</sub> = - 250 μA                                                                                                    |       | - 13   |        | mV/°C |
| V <sub>GS(th)</sub> Temperature Coefficient                     | ΔV <sub>GS(th)</sub> /T <sub>J</sub> |                                                                                                                              |       | 2.6    |        |       |
| Gate-Source Threshold Voltage                                   | V <sub>GS(th)</sub>                  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA                                                                | - 0.5 |        | - 1.2  | V     |
| Gate-Source Leakage                                             | I <sub>GSS</sub>                     | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 12 V                                                                              |       |        | ± 60   | μA    |
|                                                                 |                                      | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 4.5 V                                                                             |       |        | ± 1    |       |
| Zero Gate Voltage Drain Current                                 | I <sub>DSS</sub>                     | V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V                                                                              |       |        | - 1    |       |
|                                                                 |                                      | V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C                                                      |       |        | - 10   |       |
| On-State Drain Current <sup>a</sup>                             | I <sub>D(on)</sub>                   | V <sub>DS</sub> ≤ - 5 V, V <sub>GS</sub> = - 4.5 V                                                                           | - 20  |        |        | A     |
| Drain-Source On-State Resistance <sup>a</sup>                   | R <sub>DS(on)</sub>                  | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 7 A                                                                            |       | 0.0135 | 0.0165 | Ω     |
|                                                                 |                                      | V <sub>GS</sub> = - 3.7 V, I <sub>D</sub> = - 5 A                                                                            |       | 0.0150 | 0.0185 |       |
|                                                                 |                                      | V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 5 A                                                                            |       | 0.0210 | 0.0300 |       |
| Forward Transconductance <sup>a</sup>                           | g <sub>fs</sub>                      | V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 7 A                                                                             |       | 29     |        | S     |
| Dynamic <sup>b</sup>                                            |                                      |                                                                                                                              |       |        |        |       |
| Input Capacitance                                               | C <sub>iss</sub>                     | V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz                                                                   |       | 2130   |        | pF    |
| Output Capacitance                                              | C <sub>oss</sub>                     |                                                                                                                              |       | 290    |        |       |
| Reverse Transfer Capacitance                                    | C <sub>rss</sub>                     |                                                                                                                              |       | 280    |        |       |
| Total Gate Charge                                               | Q <sub>g</sub>                       | V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 12 A                                                  |       | 48     | 72     | nC    |
| Gate-Source Charge                                              |                                      | V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 12 A                                                 |       | 23     | 35     |       |
|                                                                 | Q <sub>gs</sub>                      |                                                                                                                              |       | 3.1    |        |       |
| Gate-Drain Charge                                               | Q <sub>gd</sub>                      |                                                                                                                              |       | 6.7    |        |       |
| Gate Resistance                                                 | R <sub>g</sub>                       | f = 1 MHz                                                                                                                    | 1.2   | 6      | 12     | Ω     |
| Turn-On Delay Time                                              | t <sub>d(on)</sub>                   | V <sub>DD</sub> = - 10 V, R <sub>L</sub> = 1 Ω<br>I <sub>D</sub> ≅ - 9.5 A, V <sub>GEN</sub> = - 4.5 V, R <sub>g</sub> = 1 Ω |       | 25     | 50     | ns    |
| Rise Time                                                       | t <sub>r</sub>                       |                                                                                                                              |       | 25     | 50     |       |
| Turn-Off Delay Time                                             | t <sub>d(off)</sub>                  |                                                                                                                              |       | 55     | 110    |       |
| Fall Time                                                       | t <sub>f</sub>                       |                                                                                                                              |       | 20     | 40     |       |
| Turn-On Delay Time                                              | t <sub>d(on)</sub>                   | V <sub>DD</sub> = - 10 V, R <sub>L</sub> = 1 Ω<br>I <sub>D</sub> ≅ - 9.5 A, V <sub>GEN</sub> = - 10 V, R <sub>g</sub> = 1 Ω  |       | 7      | 15     |       |
| Rise Time                                                       | t <sub>r</sub>                       |                                                                                                                              |       | 10     | 20     |       |
| Turn-Off Delay Time                                             | t <sub>d(off)</sub>                  |                                                                                                                              |       | 60     | 120    |       |
| Fall Time                                                       | t <sub>f</sub>                       |                                                                                                                              |       | 17     | 35     |       |
| Drain-Source Body Diode Characteristics                         |                                      |                                                                                                                              |       |        |        |       |
| Continuous Source-Drain Diode Current                           | I <sub>S</sub>                       | T <sub>C</sub> = 25 °C                                                                                                       |       |        | - 12   | A     |
| Pulse Diode Forward Current                                     | I <sub>SM</sub>                      |                                                                                                                              |       |        | - 50   |       |
| Body Diode Voltage                                              | V <sub>SD</sub>                      | I <sub>S</sub> = - 9.5 A, V <sub>GS</sub> = 0 V                                                                              |       | - 0.8  | - 1.2  | V     |
| Body Diode Reverse Recovery Time                                | t <sub>rr</sub>                      | I <sub>F</sub> = - 9.5 A, dI/dt = 100 A/μs,<br>T <sub>J</sub> = 25 °C                                                        |       | 15     | 30     | ns    |
| Body Diode Reverse Recovery Charge                              | Q <sub>rr</sub>                      |                                                                                                                              |       | 5      | 10     | nC    |
| Reverse Recovery Fall Time                                      | t <sub>a</sub>                       |                                                                                                                              |       | 7      |        | ns    |
| Reverse Recovery Rise Time                                      | t <sub>b</sub>                       |                                                                                                                              |       | 8      |        |       |

Notes:

a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

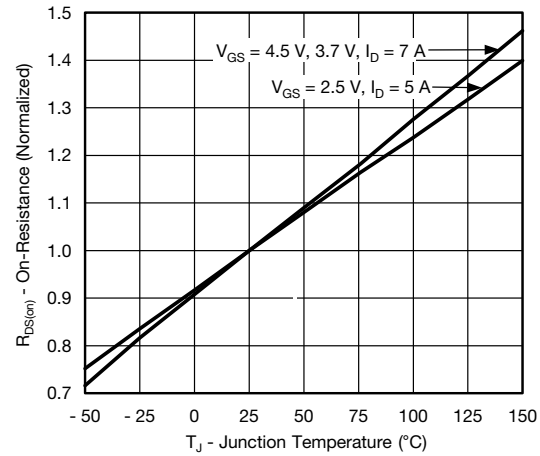
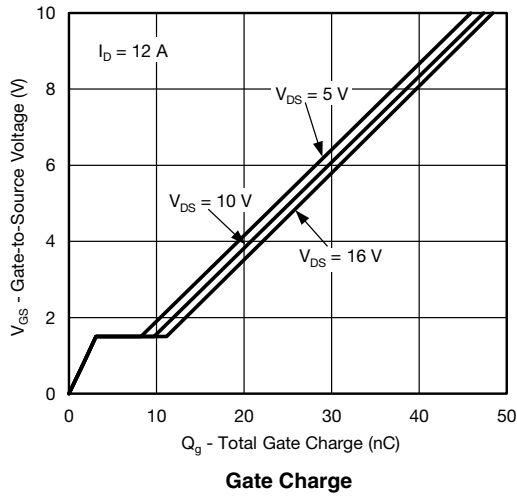
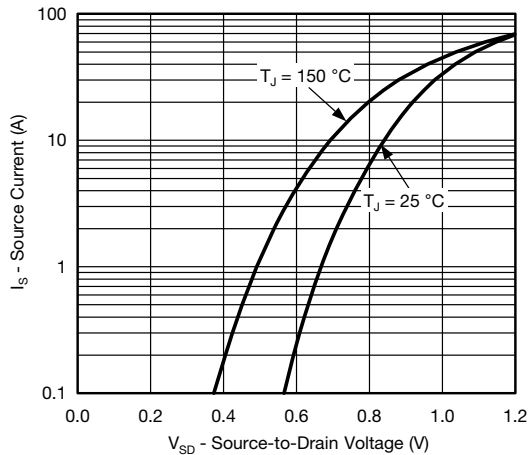
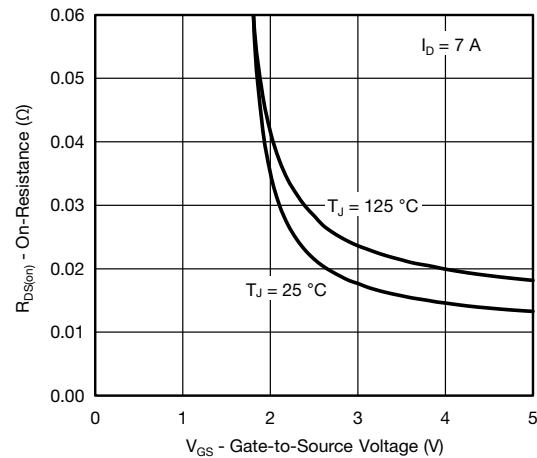
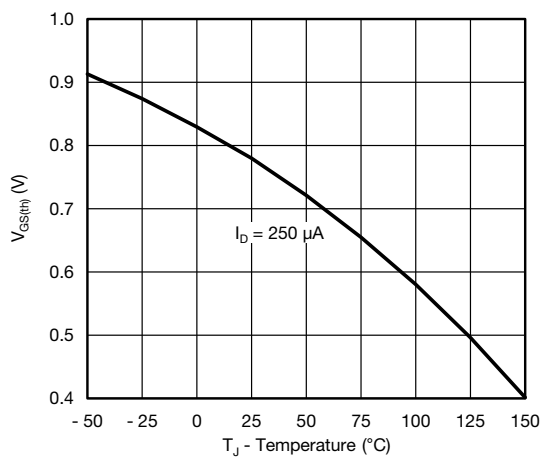
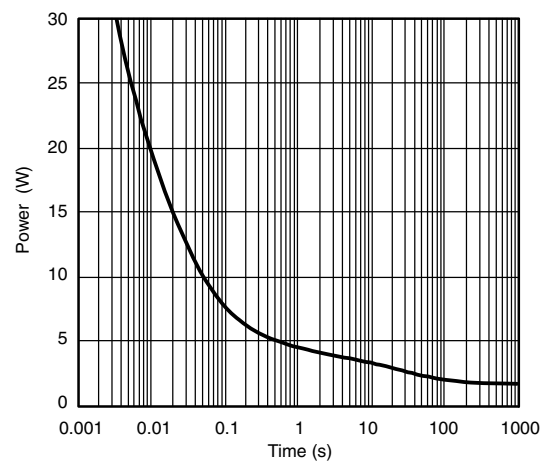
b. Guaranteed by design, not subject to production testing.

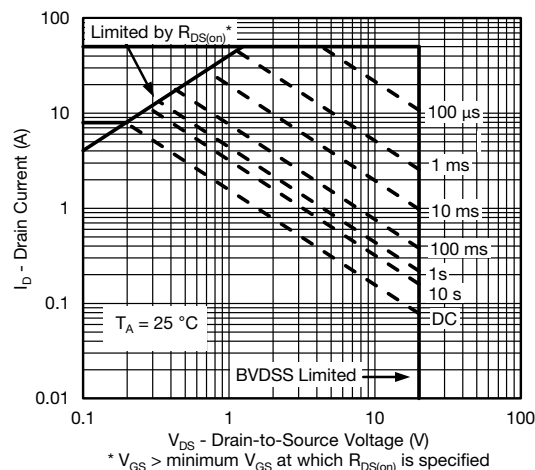
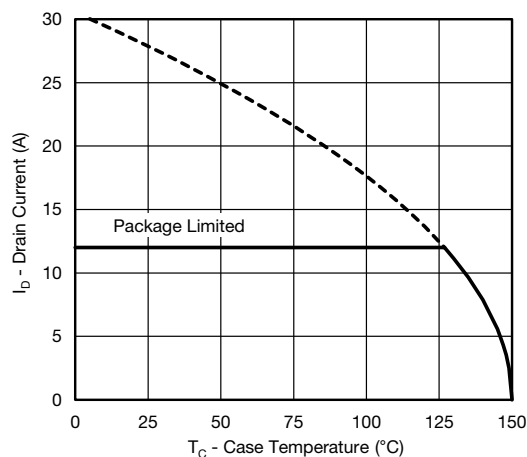
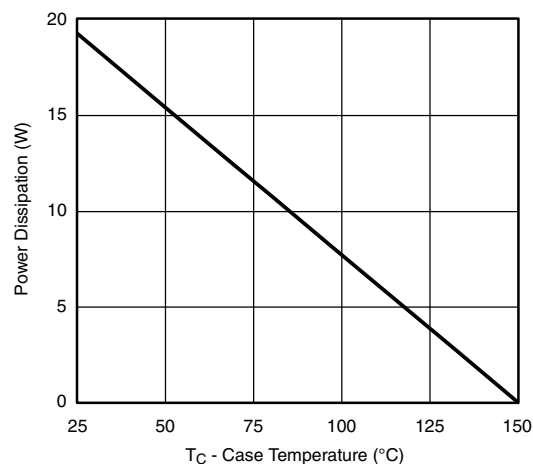
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.


**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Gate Current vs. Gate-Source Voltage**

**Gate Current vs. Gate-Source Voltage**

**Output Characteristics**

**Transfer Characteristics**

**On-Resistance vs. Drain Current**

**Capacitance**

## SiA445EDJ

Vishay Siliconix

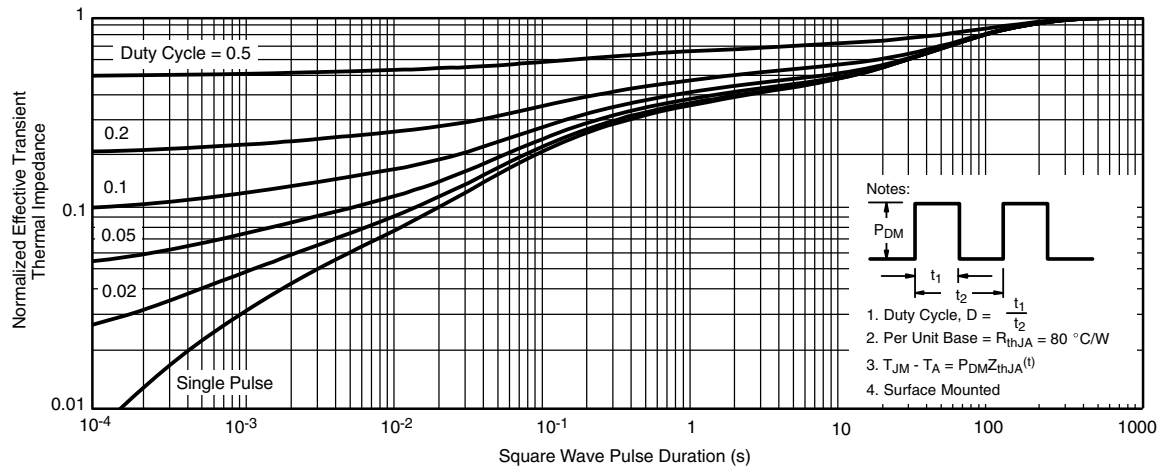
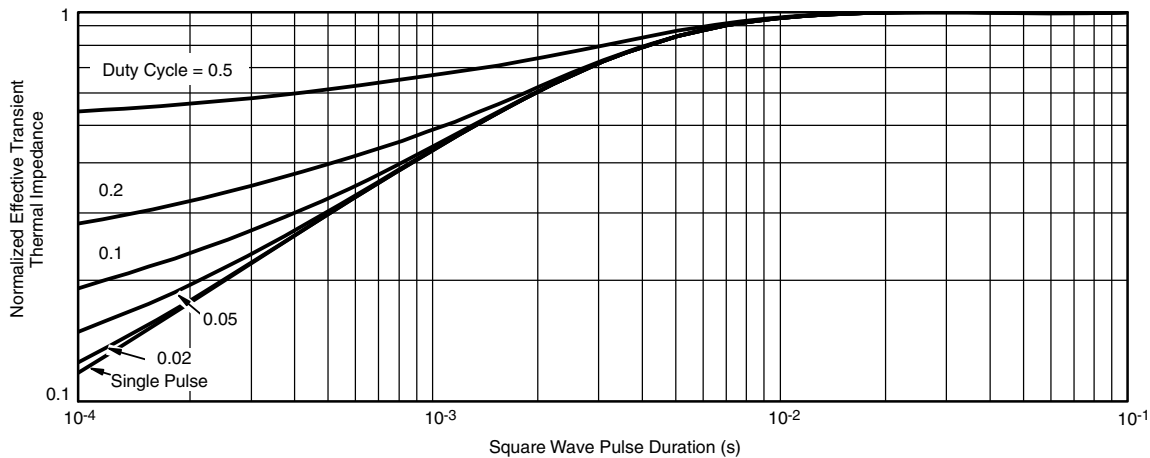
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)**On-Resistance vs. Junction Temperature****Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power, Junction-to-Ambient**


**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Safe Operating Area, Junction-to-Ambient**

**Current Derating\***

**Power Derating**

\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150\text{ }^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

## SiA445EDJ

Vishay Siliconix

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)**Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Case**

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?63619](http://www.vishay.com/ppg?63619).



## PowerPAK® SC70-6L



BACKSIDE VIEW OF SINGLE



BACKSIDE VIEW OF DUAL



### Notes:

1. All dimensions are in millimeters
2. Package outline exclusive of mold flash and metal burr
3. Package outline inclusive of plating

| DIM                                           | SINGLE PAD  |       |       |           |       |       | DUAL PAD    |       |       |           |       |       |
|-----------------------------------------------|-------------|-------|-------|-----------|-------|-------|-------------|-------|-------|-----------|-------|-------|
|                                               | MILLIMETERS |       |       | INCHES    |       |       | MILLIMETERS |       |       | INCHES    |       |       |
|                                               | Min         | Nom   | Max   | Min       | Nom   | Max   | Min         | Nom   | Max   | Min       | Nom   | Max   |
| A                                             | 0.675       | 0.75  | 0.80  | 0.027     | 0.030 | 0.032 | 0.675       | 0.75  | 0.80  | 0.027     | 0.030 | 0.032 |
| A1                                            | 0           | -     | 0.05  | 0         | -     | 0.002 | 0           | -     | 0.05  | 0         | -     | 0.002 |
| b                                             | 0.23        | 0.30  | 0.38  | 0.009     | 0.012 | 0.015 | 0.23        | 0.30  | 0.38  | 0.009     | 0.012 | 0.015 |
| C                                             | 0.15        | 0.20  | 0.25  | 0.006     | 0.008 | 0.010 | 0.15        | 0.20  | 0.25  | 0.006     | 0.008 | 0.010 |
| D                                             | 1.98        | 2.05  | 2.15  | 0.078     | 0.081 | 0.085 | 1.98        | 2.05  | 2.15  | 0.078     | 0.081 | 0.085 |
| D1                                            | 0.85        | 0.95  | 1.05  | 0.033     | 0.037 | 0.041 | 0.513       | 0.613 | 0.713 | 0.020     | 0.024 | 0.028 |
| D2                                            | 0.135       | 0.235 | 0.335 | 0.005     | 0.009 | 0.013 |             |       |       |           |       |       |
| E                                             | 1.98        | 2.05  | 2.15  | 0.078     | 0.081 | 0.085 | 1.98        | 2.05  | 2.15  | 0.078     | 0.081 | 0.085 |
| E1                                            | 1.40        | 1.50  | 1.60  | 0.055     | 0.059 | 0.063 | 0.85        | 0.95  | 1.05  | 0.033     | 0.037 | 0.041 |
| E2                                            | 0.345       | 0.395 | 0.445 | 0.014     | 0.016 | 0.018 |             |       |       |           |       |       |
| E3                                            | 0.425       | 0.475 | 0.525 | 0.017     | 0.019 | 0.021 |             |       |       |           |       |       |
| e                                             | 0.65 BSC    |       |       | 0.026 BSC |       |       | 0.65 BSC    |       |       | 0.026 BSC |       |       |
| K                                             | 0.275 TYP   |       |       | 0.011 TYP |       |       | 0.275 TYP   |       |       | 0.011 TYP |       |       |
| K1                                            | 0.400 TYP   |       |       | 0.016 TYP |       |       | 0.320 TYP   |       |       | 0.013 TYP |       |       |
| K2                                            | 0.240 TYP   |       |       | 0.009 TYP |       |       | 0.252 TYP   |       |       | 0.010 TYP |       |       |
| K3                                            | 0.225 TYP   |       |       | 0.009 TYP |       |       |             |       |       |           |       |       |
| K4                                            | 0.355 TYP   |       |       | 0.014 TYP |       |       |             |       |       |           |       |       |
| L                                             | 0.175       | 0.275 | 0.375 | 0.007     | 0.011 | 0.015 | 0.175       | 0.275 | 0.375 | 0.007     | 0.011 | 0.015 |
| T                                             |             |       |       |           |       |       | 0.05        | 0.10  | 0.15  | 0.002     | 0.004 | 0.006 |
| ECN: C-07431 – Rev. C, 06-Aug-07<br>DWG: 5934 |             |       |       |           |       |       |             |       |       |           |       |       |

## RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Single



Dimensions in mm/(Inches)

[Return to Index](#)



## Disclaimer

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**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**

## Данный компонент на территории Российской Федерации

**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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